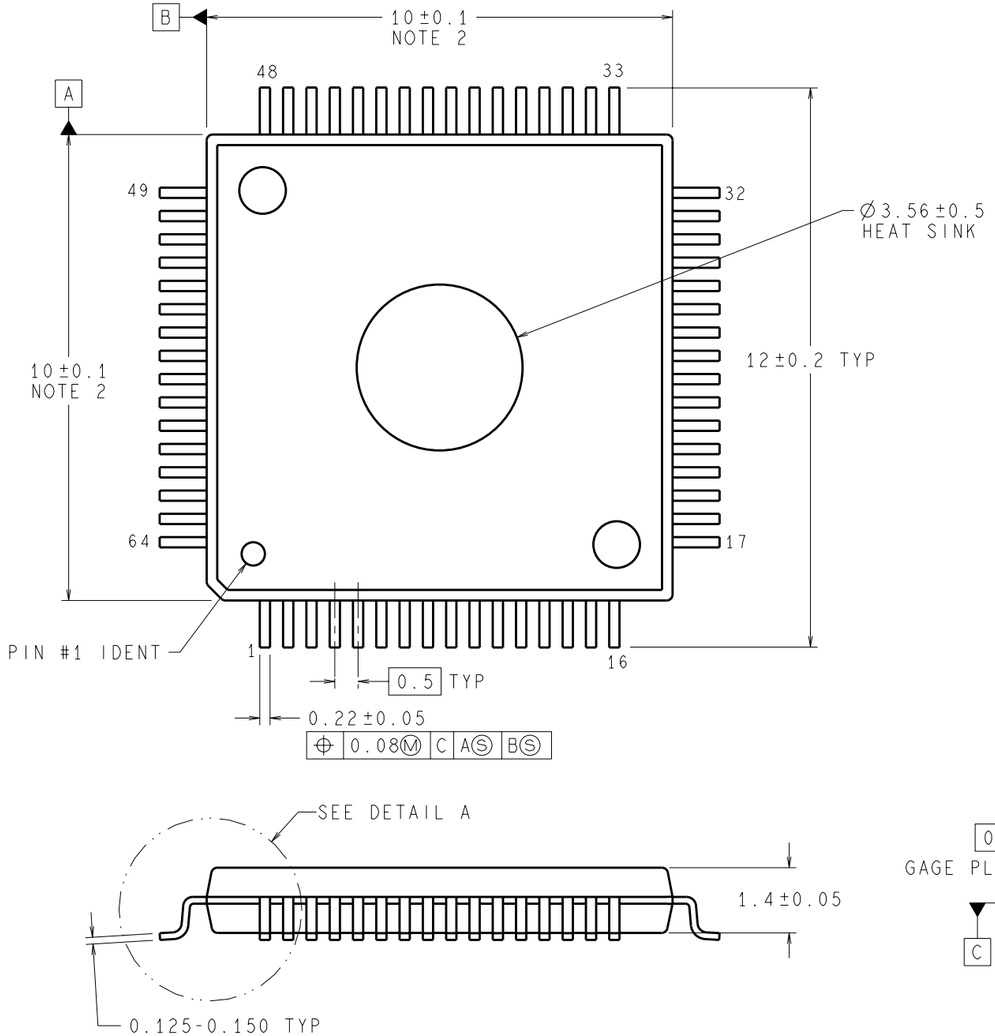
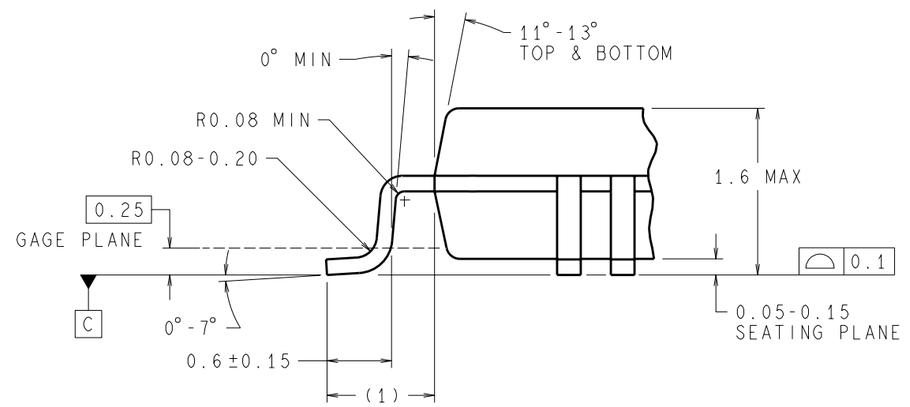
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11589	10/07/1996	MS/SM
B	TITLE: LQFP WAS TQFP; UPDATE NOTE 3; ADD GEOMETRIC TOLERANCE	12317	11/10/1999	TL/RW





DETAIL A
TYP, SCALE: 30X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:
   7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
   THICKNESS ON ALLOY 42/ COPPER.

2. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
   MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.

3. REFERENCE JEDEC STANDARD MS-026, VARIATION BCD,
   DATED FEBRUARY 1999.

APPROVALS	DATE
DRAWN MARTA SUCHY	10/07/1996
DFTG. CHK. MARTA SUCHY	11/10/1999
ENGR. CHK. RANDY WALBERG	11/10/1999

PROJECTION
INCH (MM)

National Semiconductor
2900 Semiconductor Dr., Santa Clara, CA 95052-8090

LQFP, JEDEC METRIC, 10 X 10 X 1.4mm, 64 LEAD, EXPOSED H/S

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-VEV64A	B

FORMERLY: N/A

SHEET 1 of 1